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Date: June 16, 2003	Client & Matter Number : 015114-052310US	No. Pages (including this one): 2
To: Examiner Nitin Parekh Art Unit 2811 U.S. Patent and Trademark Office	At Fax Number: 1 (703) 308-7722, 4	Confirmation Phone Number:
From : Melvin D. Chan	FAX RECEIVED	
	JUN 16 2003 (x521)	

Message: TECHNOLOGY CENTER 2800

Re: **U.S. Patent Application 09/517,345 for
METHOD AND STRUCTURE FOR INTEGRATED CIRCUIT PACKAGE
Our File: +015114-052310US**

Dear Examiner Parekh:

Enclosed is our agenda for the interview tomorrow scheduled for 2:00 p.m. your time.

Melvin D. Chan

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Outline for Interview
Application No. 09/517,345

1. Motivation to Combine

- a. Zenner - Ultra-thin package
Schueller - Standard thickness package
- b. Zenner - Flexibility after assembly
Schueller - Package flatness and coplanarity
- c. Schueller - Decouple die from substrate
Welkowsky - Directly bond die to substrate

2. Discuss combination of (1) Schueller and (2) Zenner and (3) Welkowsky

3. Discuss potential allowable claim language

- a. Examiner's suggestions
- b. Applicant's suggestions

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